

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6630331

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YAKU MAEDA	02/15/2021
YOSHINOBU HOSHINO	02/15/2021
KIMINORI TOYOOKA	03/02/2021
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECH CORPORATION
Street Address:	17-1, TORANOMON 1-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
Name:	RIKEN
Street Address:	2-1, HIROSAWA
City:	WAKO-SHI, SAITAMA
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17281296
CORRESPONDENCE DATA	
Fax Number:	(202)628-8844
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Email:	asaguros@crowell.com, edocket@crowell.com
Correspondent Name:	CROWELL & MORING LLP
Address Line 1:	P.O. BOX 14300
Address Line 4:	WASHINGTON, D.C. 20044-4300
ATTORNEY DOCKET NUMBER:	109701.PE433US
NAME OF SUBMITTER:	MICHAEL H. JACOBS
SIGNATURE:	/Michael H. Jacobs/
DATE SIGNED:	03/30/2021
Total Attachments: 3	

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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to the below named inventor(s), citizens of Japan by Hitachi High-Tech Corporation and RIKEN, corporations organized under the laws of Japan, located at 17-1, Toranomon 1-chome, Minato-ku, Tokyo, Japan and 2-1, Hirasawa, Wako-shi, Saitama, Japan, respectively, receipt of which is hereby acknowledged, we, the below named inventor(s), do hereby sell and assign to said Hitachi High-Tech Corporation and RIKEN, their successors and assigns, all our right, title and interest, in and for the United States of America, in and to

ALIGNMENT SYSTEM AND SEAL FOR POSITIONAL ALIGNMENT

invented by us and described in the application for United States Letters Patent thereto, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Tech Corporation and RIKEN, their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made;

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Tech Corporation and RIKEN,

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Yaku MAEDA <i>Yaku Maeda</i>	<i>2/15/2021</i>
2)	Yoshinobu HOSHINO	
3)	Kiminori TOYOOKA	
4)		
5)		
6)		
7)		
8)		
9)		
10)		

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Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

- 1) Yaku MAEDA _____
- 2) Yoshinobu HOSHINO *Yoshinobu Hoshino* _____ 2/15/2021
- 3) Kiminori TOYOOKA _____
- 4) _____
- 5) _____
- 6) _____
- 7) _____
- 8) _____
- 9) _____
- 10) _____

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1)	<u>Yaku MAEDA</u>	_____
2)	<u>Yoshinobu HOSHINO</u>	_____
3)	<u>Kiminori TOYOOKA</u> <i>Kiminori Toyooka</i>	<u>Mar. 2, 2021</u>
4)	_____	_____
5)	_____	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____

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